

MAINTENANCE MANUAL 138—174 MHz RF ASSEMBLY 19D416693G1, G2, G7, G8 AND

MIXER/IF BOARD 19C320153GI

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DESCRIPTION

The RF Assembly uses five tuned helical resonators to provide front end RF selectivity with no gain. A UHS pre-amplifier assembly is available that can be used with the receiver to improve sensitivity.

The Mixer/IF board (MIF) uses the RF signal from the RF Assembly and the mixer injection frequency from the oscillator multiplier board to generate the IF frequency.

CIRCUIT ANALYSIS

RF ASSEMBLY

RF PRE-AMPLIFIER (Optional)

The pre-amplifier is present only in UHS receivers, and uses a dual-gate Field Effect Transistor (FET) to provide approximately 12 dB gain.

RF from the antenna is coupled through T2301 to Gate 1 of pre-amplifier Q2301. The primary of T2301 provides a 50-ohm input impedance. The amplified output at the drain terminal of Q2301 is coupled through T2302 and connected to J1 on Antenna Input board A301 through cable W2302. T2302 is tapped to provide a 50-ohm output impedance. P2301 connects to J501 on the MIF board for the regulated +10 Volt supply voltage.

ANTENNA INPUT A301/A301B

An RF signal from the antenna or UHS pre-amplifier is applied to A301 which provides an AC ground between vehicle ground and receiver A-. Resistor R1 prevents a static charge from building up on the vehicle antenna. The output of A301 is coupled through five high Q helical resonators that provide the front end RF selectivity. The helicals are tuned to the incoming frequency by C301 through C305.

MIXER-IF

MIXER & CRYSTAL FILTER

The mixer uses a FET (Q501) as the active device. The FET mixer provides a high input impedance, high power gain, and an output relatively free of harmonics (low in intermodulation products).

In the mixer stage, RF from the helical resonators is coupled through L502 and C502 which matches the RF output to the gate of mixer Q501. Injection voltage from the multiplier-selectivity stages is inductively coupled through L501 to the source of the mixer. The 11.2 MHz mixer IF output signal is coupled from the drain of Q501 through a tuned circuit (L505 and C505) which matches the mixer output to the input of the four-pole monolithic crystal filter. The highly-selective crystal filter (FL501 and FL502) provides the first portion of the receiver IF selectivity. The output of

the filter is coupled through impedancematching network L520 and C523 to the IF amplifier.

Service Note: Variable capacitor C521 does not require adjustment when performing normal alignment. If the four-pole monolithic crystal filter is replaced, then adjustment of C521 is necessary for optimum IF response.

IF AMPLIFIER

 $\,$ IF amplifier Q520 is a dual-gate FET. The filter output is applied to Gate 1 of

the amplifier, and the output is taken from the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain.

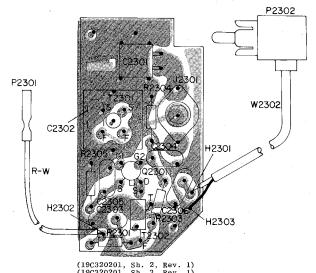
The output of Q520 is coupled through impedance matching network L521, and C528 and coupling capacitor C529 and feed-through capacitor C325 to the next IF stage on to the MIF switch in Dual Front End Applications.

Supply voltage for the RF amplifier and MIF board is supplied through feed-through capacitor C326.

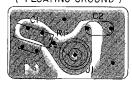
MOBILE RADIO DEPARTMENT
GENERAL ELECTRIC COMPANY • LYNCHBURG, VIRGINIA 24502



UHS PRE-AMPLIFIER

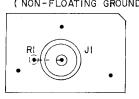


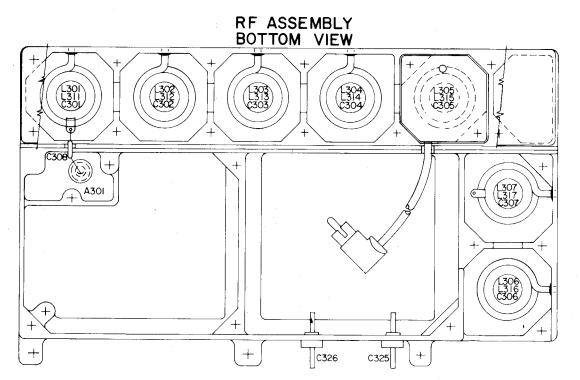
A 3 OI A
ANT INPUT
(FLOATING GROUND)



(19B219679, Sh. 2, Rev. 2) (19B219679, Sh. 3, Rev. 2)







(19D423618, Rev. 2)

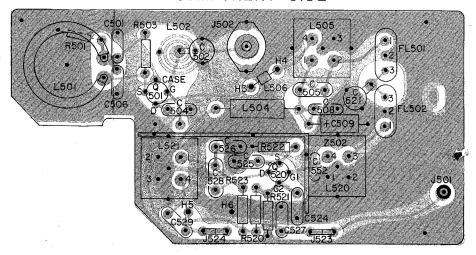
RUNS ON SOLDER SIDE

RUNS ON BOTH SIDES

RUNS ON COMPONENT SIDE

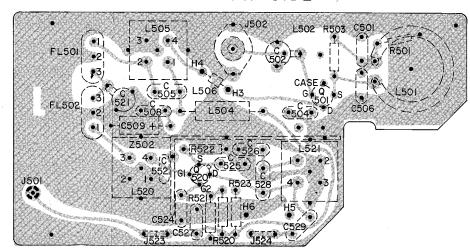
MIXER/IF BOARD

COMPONENT SIDE



(19C321054, Sh. 2, Rev. 1) (19C321054, Sh. 3, Rev. 0)

SOLDER SIDE



(19C321054, Sh. 2, Rev. 1)

FOR Q501 Q520, Q2301

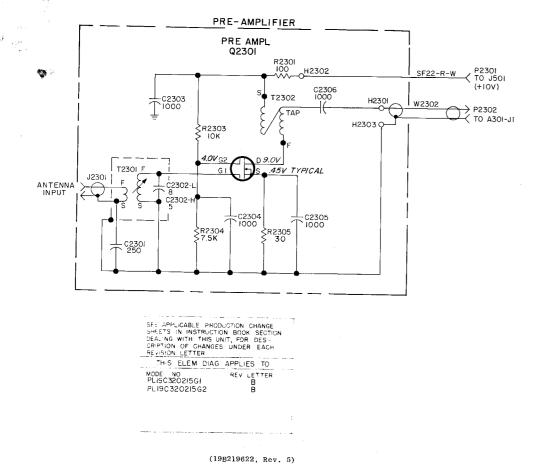
VIEW FROM CASE END

LEAD IDENTIFICATION

NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

OUTLINE DIAGRAM

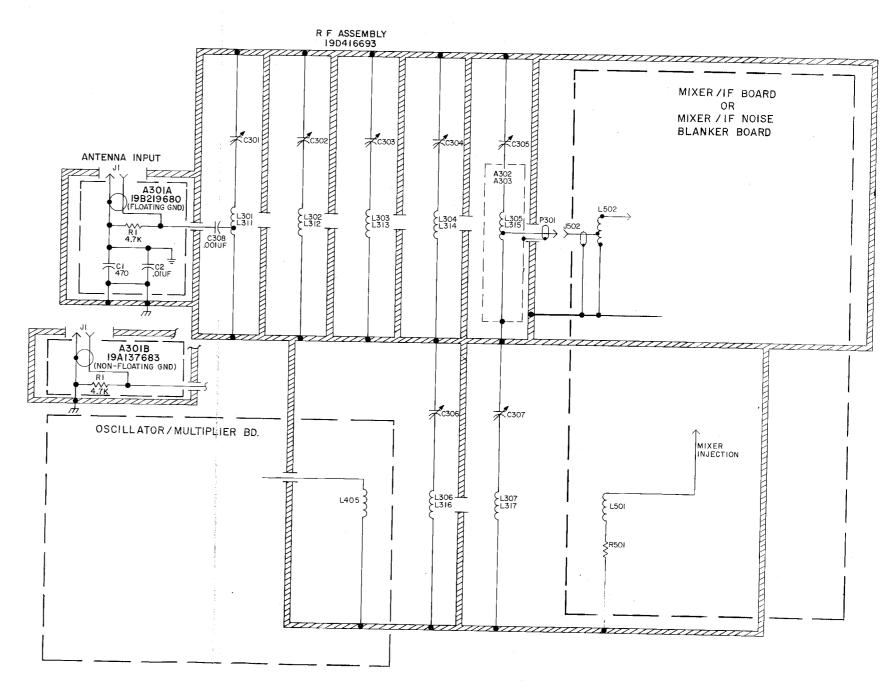
138—174 MHZ RF ASSEMBLY AND MIXER/IF BOARD



SCHEMATIC DIAGRAM

138—174 MHZ RF ASSEMBLY

Issue 2



ANTENNA INPUT A301		RF ASSEMBLY		FREQ RANGE (MHZ)
	REV LTR	-	REV LTR	
19B2;9680GI	- 1	19D416693G1	В	138-155
19B2I9680GI	- 1	19D416693G2	С	150.8-174
19A137683GI		19D416693G7		138-155
19A137683GI	-	19D416693G8	-	150.8-174

ALL RESISTORS ARE 1/4 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K=1000 OHMS OF MEGET IN PROFARADS (EQUAL TO MICROMICROFARADS) UNLESS FOLLOWED BY UF- MICROFARADS. INDUCTANCE VALUES IN MICROFIENTYS UNLESS FOLLOWED BY MH=MILLIHENRYS OR H=HENRYS.

IN ORDER, TO RETAIN RATED EQUIPMENT PERFORMANCE, REPLACEMENT OF ANY SERVICE PART SHOULD BE MADE ONLY WITH A COMPONENT HAVING THE SPECIFICATIONS SHOWN ON THE PARTS LIST FOR THAT PART.

VOLTAGE READINGS

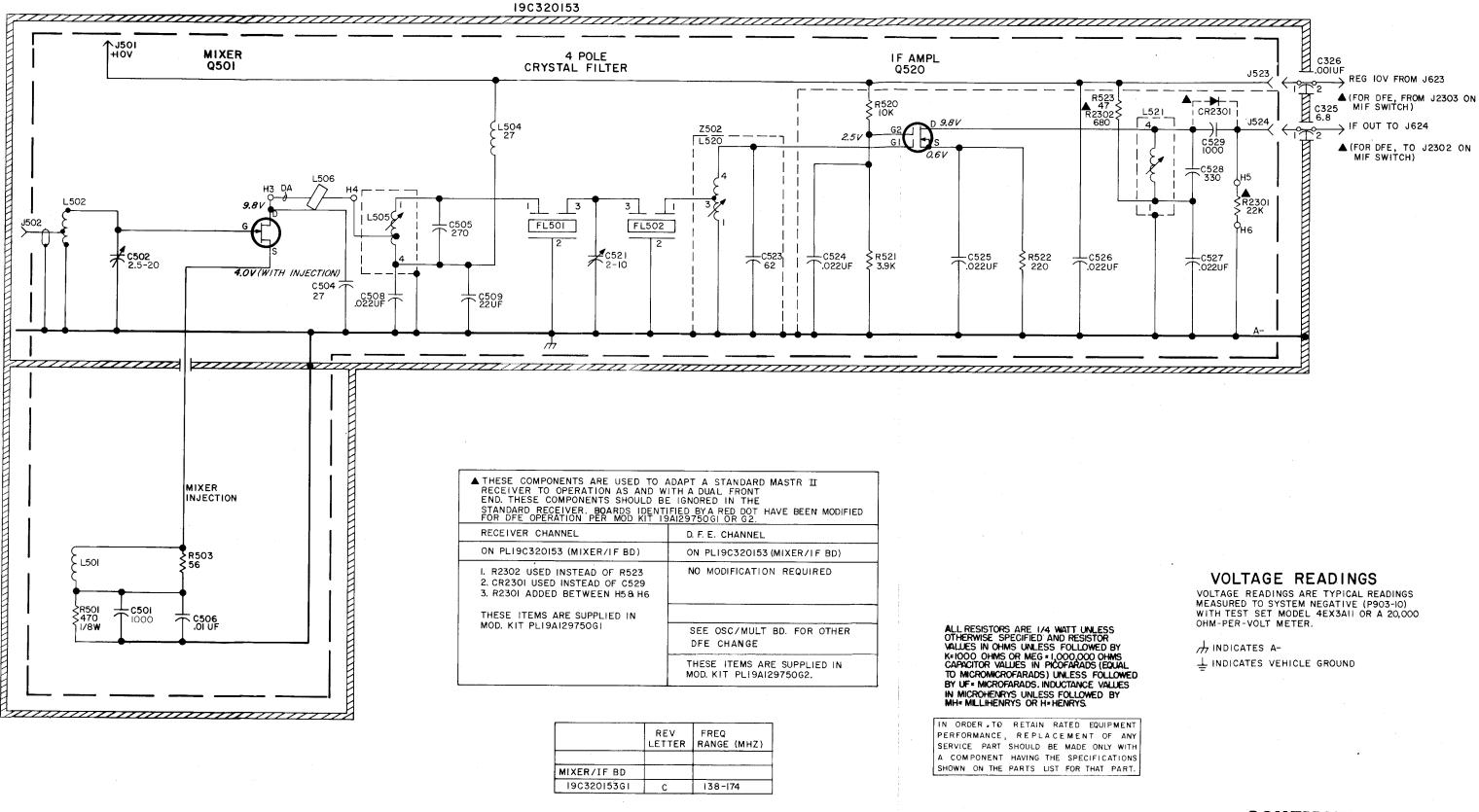
VOLTAGE READINGS ARE TYPICAL READINGS MEASURED TO SYSTEM NEGATIVE (P903-10) WITH TEST SET MODEL 4EX3AII OR A 20,000 OHM-PER-VOLT METER.

INDICATES A-

INDICATES VEHICLE GROUND

(19D423469, Rev. 1)

MIXER/IF BD 190320153



(19D423478, Rev. 2)

SCHEMATIC DIAGRAM

138—174 MHZ MIXER/IF BOARD

PARTS LIST

LB14981C

138-174 MHz RF ASSEMBLY, MIF ASSEMBLY, UHS PRE-AMPLIFIER

SYMBOL	GE PART NO.	DESCRIPTION
		RF ASSEMBLY 19D416693G1 138-155 MHz FLOATING GRD 19D416693G2 150.8-174 MHz FLOATING GRD 19D416693G8 138-155 MHz NON FLOATING GRD 19D416693G8 150.8-174 MHz NON FLOATING GRD
A301A		ANTENNA INPUT BOARD 19B219680G1
Cl	19A116679P470K	Mica: 470 pf ±10%, 250 VDCW.
C2	19A116080P101	Polyester: 0.01 µf ±10%, 50 VDCW.
		JACKS AND RECEPTACLES
J1	7104941P16	Connector, phono: Jack; sim to National Tel.
	:	
R1	3R152P472J	Composition: 4.7K ohms ±5%, 1/4 w.
A301B		ANTENNA INPUT PLATE
		19A137683G1
		JACKS AND RECEPTACLES
J1	7104941P16	Connector, phono: Jack; sim to National Tel. Barrel Ceramic.
		RESISTORS
R1	3R152P472J	Composition: 4.7K ohms ±5%, 1/4 w.
A302 and A303		COMPONENT BOARD A302 19B226512G1 138-155 MHz A303 19B226512G2 150.8-174 MHz
L305	19B216112G20	Coil,
L315	19B216112G21	Coil,
P301	5491689P85	Cable, RF: approx 4 inches long, 350 VRMS, 500 VDC operating voltage.
C301		Includes:
thru C305	4036765G11	Screw.
	7137968P8	Nut, stamped: thd size No. 6-32; sim to Palnut
C306*		TO632005. Includes:
and C307*		
	4036765G11	Screw. (Added to G2 by REV C).
	4036765G12 7137968P8	Screw. (Deleted in G2 by REV C). Nut, stamped: thd size No. 6-32; sim to Palnut
		T0632005.
C308	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C325	19B209488P1	Ceramic, feed-thru: 6.8 pf $\pm 20\%$, 500 VDCW; sim to Allen-Bradley Style FA5D.
C326	19B209488P2	Ceramic, feed-thru: 1000 pf +100% -0%, 500 VDCW; sim to Allen-Bradley Style FA5H.
L301	19B216112G19	Coil.
L302 thru	19B216112G11	Coil.
L304		

SYMBOL	GE PART NO.	DESCRIPTION	
			-
L306 and L307	19B204461G18	Coil.	
L311	19B216112G17	Coil.	
L312 thru L314	19B216112G15	Coil.	
L316 and L317	19B204461G19	Coil.	
1317			
	19E500969G1	Casting.	
	19C320251P1	Cover.	
	19B209209P305	Tap screw, Phillips POZIDRIV®: No. 6-32 x 5/16. (Secures cover).	
	19B201074P304	Tap screw, Phillips POZIDRIV®: No. 6-32 x 1/4. (Used with A301-A303).	
		MIF ASSEMBLY 19C320153G1	
C501	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.	
C502	19B209351P2	Variable, ceramic: 2.5 to 20 pf, 200 VDCW, temp coef -250 +700 PPM/°C; sim to Matshushita ECV-1Z-W20P32.	
C504	19Al16656P27K0	Ceramic disc: 27 pf ±10%, 500 VDCW, temp coef 0 PPM.	
C505	7489162P37	Silver mica: 270 pf ±5%, 500 VDCW; sim to Electro Motive Type DM-15.	
C506	19A116080P101	Polyester: 0.01 μf ±10%, 50 VDCW.	
C508	19A116080P103	Polyester: 0.022 µf ±10%, 50 VDCW.	
C509	5496267P10	Tantalum: 22 μ f $\pm 20\%$, 15 VDCW; sim to Sprague Type 150D.	
C521	19B209351Pl	Variable: 2 to 10 pf, 200 VDCW, temp coef -350 to +500 PPM/°C; sim to Matshushita ECV-1ZW10P32.	
C523		(Part of Z502).	
C524 thru C527	19A116080P3	Polyester: 0.022 μf ±20%, 50 VDCW.	
C528	5490008P139	Silver mica: 330 pf ±10%, 500 VDCW; sim to Electro Motive Type DM-15.	
C529	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.	
E10 and E11	19B209055P8	Terminal, feed-thru: sim to Electrical Ind. ABAS40WSS.	
FL501	19B219573G7	Crystal, freq: Resonator A: 11,200000 KHz, Resonator B: 11,196024 KHz, Resonator A: 11,200000 KHz,	
FL502		Resonator B: 11,196024 KHz.	
		JACKS AND RECEPTACLES	
J501	4033513P1	Contact, electrical: sim to Bead Chain L93-4.	
	19A130924G1	Receptacle, coaxial: sim to Cinch 14H11613.	
J502 J523	19A130924G1 19A116975P1	Receptacle, wire spring.	
and J524	19411097391	neceptation, with spring.	
L501	19A129280P1	Coil.	
L502		Coil. (Part of printed wire board 19C321054P1).	
L504	7488079P48	Choke, RF: 27.0 μh $\pm 10\%$, 1.40 ohms DC res max; sim to Jeffers 4422-9K.	
L505	19C320141G30	Coil. Includes:	
	5493185P9	Tuning slug.	

SYMBOL	GE PART NO.	DESCRIPTION
1500	10410014001	
L506	19A126140P1	Core, toroidal.
L520		(Part of Z502).
L521	19C320141G6	Coil. Includes:
	5493185P9	Tuning slug.
Q501	19A134093P1	N Type, field effect; sim to Type 2N4391.
Q520	19A116818P1	N Channel, field effect; sim to Type 3N187.
V		the commentary are the control of th
		RESISTORS
R501	3R151P471J	Composition: 470 ohms ±5%, 1/8 w.
R503	3R152P560K	Composition: 56 ohms ±10%, 1/4 w.
R520	3R152P103K	Composition: 10K ohms ±10%, 1/4 w.
R521	3R152P392J	Composition: 3.9K ohms ±5%, 1/4 w.
R522	3R152P221J	Composition: 220 ohms ±5%, 1/4 w.
R523	3R152P470J	Composition: 47 ohms ±5%, 1/4 w.
Z502		COIL ASSEMBLY
		19C320141G20
C523	19A116114P1057	Ceramic: 62 pf ±5%, 100 VDCW; temp coef -30 PPM.
L520	19C320141P4	Coil.
	5493185P9	Tuning slug.
		UHS PRE-AMPLIFIER BOARD 19C320215G1 138-158 MHz 19C320215G2 147-174 MHz
C2301	19A116795P250K	Mica: 250 pf ±10%, 250 VDCW; sim to Underwood
C2301	19A110793P230A	Type J1HF.
C2302L		(Part of T230lL).
C2302H		(Part of T2301H).
C2303	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to
thru C2306		RMC Type JF Discap.
		JACKS AND RECEPTACLES
J2301	19A130924G1	Connector, receptacle: coaxial, jack type; sim
520VI		to Cinch 14H11613.
		PLUGS
D 0003	400004070	
P2301	4029840P2	Contact, electrical: sim to Amp 42827-2.
P2302		(Part of W2302).
Q2301	19Al16818P1	N Channel, field effect; sim to Type 3N187.
		RESISTORS
	3R152P101K	Composition: 100 ohms ±10%, 1/4 w.
R2301	l	Composition: 10K ohms ±10%, 1/4 w.
R2301 R2303	3R152P103K	
	3R152P103K 3R152P752J	Composition: 7.5K ohms ±5%, 1/4 w.
R2303		Composition: 7.5K ohms ±5%, 1/4 w. Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304	3R152P752J	
R2303 R2304	3R152P752J	Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304 R2305	3R152P752J	Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304	3R152P752J	Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304 R2305	3R152P752J	Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304 R2305	3R152P752J 3R152P300J	Composition: 30 ohms ±5%, 1/4 w.
R2303 R2304 R2305	3R152P752J	Composition: 30 ohms ±5%, 1/4 w.

L1 T2301H	19C320141P25 5493185P9	Coil. Tuning slug. COIL ASSEMBLY
T2301R	1	Coil. Tuning slug. COIL ASSEMBLY
T2301R	1	Tuning slug.
4		COIL ASSEMBLY
4		
: C5	i	19C320141G21
C5	1	
	5496218P305	Ceramic disc: 5.0 pf ±0.5 pf, 500 VDCW, temp coef -150 PPM.
L1	19C320141P25	Coil.
	5493185P9	Tuning slug.
T2302	19A127108G1	Coil.
W2302	5491689P85	Cable, RF: approx 4 inches long. (Includes P2302).
	-	
	19B219470P2	Shield.
	19A129424G1	Can. (Used with L505, L521, Z502 and T2301 on PRE-AMPLIFIER Board).
	4031594P1	Insulator. (Located under C502, C521).
	4035306P23	Washer, fiber. (Located under J502).
		RECEIVER MODIFICATION KIT 19A129750G1
,		
C2301	19A116656P8J0	Ceramic disc: 8 pf ±0.5 pf, 500 VDCW, temp coef 0 PPM.
		DIODES AND RECTIFIERS
CR2301	19A116925P1	Silicon, pin: 35 volt Reverse Breakdown, 400 mW.
		RESISTORS
R2301	3R152P223J	Composition: 22K ohms ±5%, 1/4 w.
R2302	3R152P681K	Composition: 680 ohms ±10%, 1/4 w.
W2301	19B219999G2	Cable: approx 1 foot long.
		DFE MODIFICATION KIT 19A129750G2
22301	19A116656P8J0	Ceramic disc: 8 pf ± 0.5 pf, 500 VDCW, temp coef 0 PPM.
]	`	RESISTORS
12303	3R152P911J	Composition: 910 ohms ±5%, 1/4 w.
	T2302 W2302 W2301 R2301 R2301 R2301	5493185P9 19A127108G1 W2302 5491689P85 19B219470P2 19A129424G1 4031594P1 4035306P23 C2301 19A116656P8J0 CR2301 19A116925P1 22302 3R152P223J 3R152P681K C2301 19B219999G2

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A thru C - Mixer/IF Board 19C320153G1

REV. A and B - RF Assembly 19D416693G1,2

REV. A and B - Preamplifier Assembly 19C320215G1,2

Incorporated in initial shipment.

REV. C - RF Assembly 19D416693G2

To improve band end tuning. Changed C306 and C307.